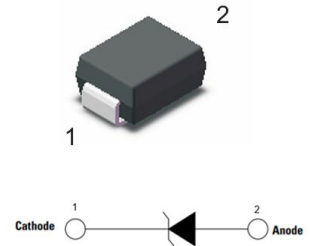


Features

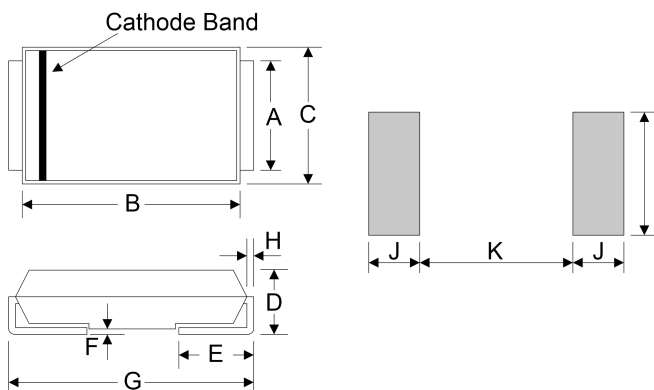
- ◆ Metal silicon junction, majority carrier conduction
- ◆ For surface mounted applications
- ◆ Low power loss, high efficiency
- ◆ High current capability, low forward voltage drop
- ◆ Meets MSL level 1, per J-STD-020
- ◆ Plastic package has underwriters laboratory flammability 94V-0
- ◆ Polarity: color band denotes cathode end



Applications

- ◆ Low voltage high frequency inverters
- ◆ DC/DC converters
- ◆ Freewheeling
- ◆ Polarity protection applications

Dimensions (DO-214AA/SMB)



Ref.	Millimeters		Inches	
	Min	Max	Min.	Max.
A	1.850	2.200	0.072	0.086
B	4.060	4.650	0.160	0.183
C	3.300	3.940	0.130	0.155
D	2.050	2.440	0.080	0.096
E	0.760	1.520	0.030	0.060
F	-	0.203	-	0.008
G	5.050	5.590	0.198	0.220
H	0.152	0.305	0.006	0.012
I	2.260	-	0.089	-
J	2.160	-	0.085	-
K	-	2.740	-	0.107

Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	SS								Unit
		32B	34B	36B	38B	310B	312B	315B	320B	
Repetitive peak reverse voltage	V _{RRM}	20	40	60	80	100	120	150	200	V
Maximum RMS Voltage	V _{RMS}	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	V _{DC}	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	I _{F(AV)}	3.0								A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	I _{FSM}	80								A
Maximum instantaneous forward voltage @3A	V _F	0.55		0.70	0.85			0.95		V
Maximum DC reverse current at rated DC blocking voltage	I _{R @25℃}	0.5			0.3					mA
	I _{R@100℃}	5			3					
Typical Junction Capacitance(Note1)	C _J	450			400					pF
Thermal resistance(Note2)	Rθ _{J-A}	60								℃/W
Junction temperature	T _j	-55~+125								℃
Storage temperature	T _{stg}	-55 ~+150								℃

Notes: 1. Measured at 1 MHz and applied reverse voltage of 4 V D.C
 2. P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Ratings and Characteristic Curves ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Figure 1. Forward Current Derating Curve

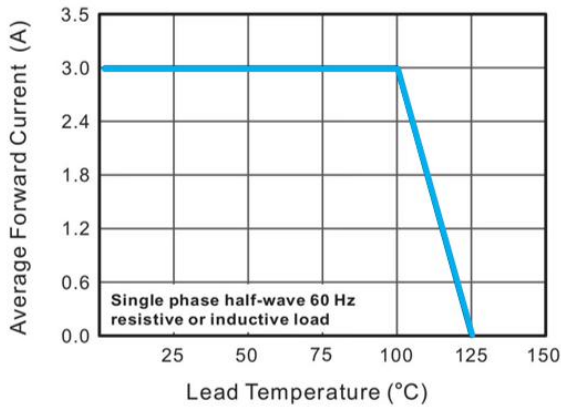


Figure 2. Typical Reverse Characteristics

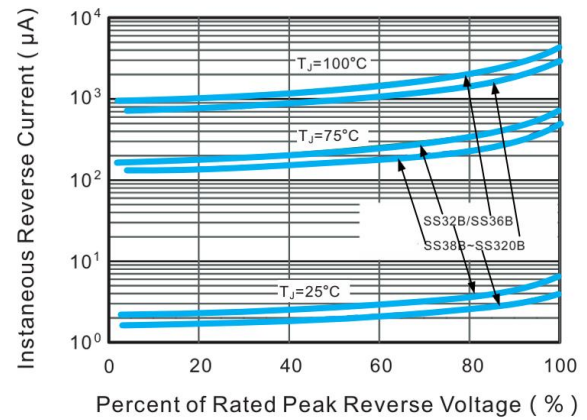


Figure 3. Typical Forward Characteristic

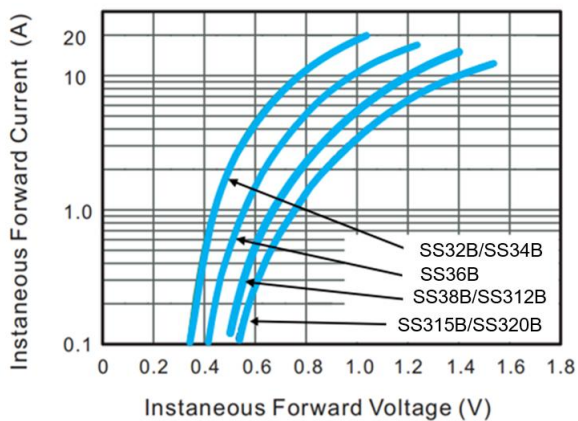


Figure 4. Typical Junction Capacitance

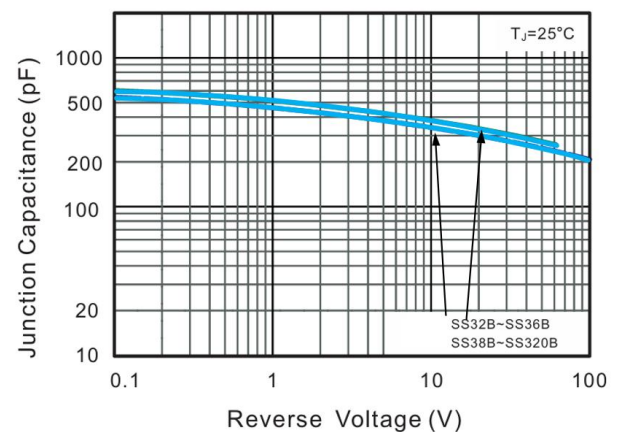


Figure 5. Maximum Non-Repetitive Peak Forward Surge Current

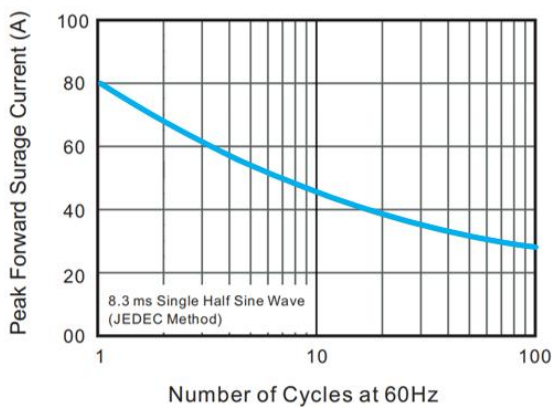
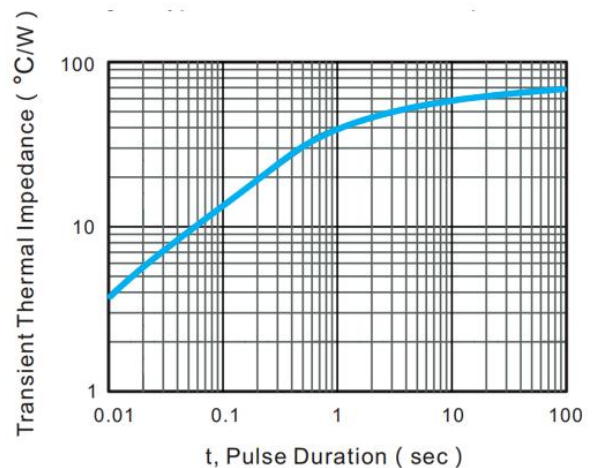
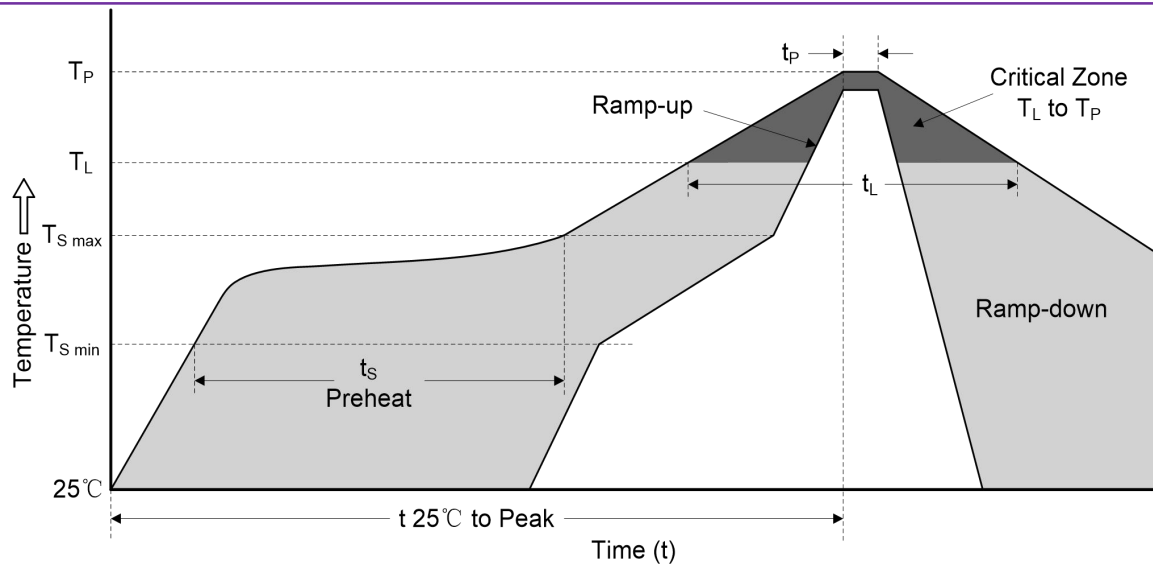


Figure 6. Typical Transient Thermal Impedance



Reflow Soldering Parameters



Reflow Condition		Lead-free Assembly
Pre heat	-Temperature Min ($T_{S\ min}$)	150°C
	-Temperature Max ($T_{S\ max}$)	200°C
	-Time (min to max) (t_s)	60-180 seconds
Average ramp-up rate (T_L to T_P)		3°C/second max.
$T_{S\ max}$ to T_L -Ramp-up Rate		3°C/second max.
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Time (min to max) (t_s)	60-150 seconds
Peak Temperature (T_P)		260(+0/-5)°C
Time within 5°C of actual Peak Temperature (t_P)		20-40 seconds
Ramp-down Rate		6°C/second max.
Time 25°C to Peak Temperature(T_P)		8 minutes max.
Do not exceed		260°C